


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L99PM72GXP	GE6H*UK40AA6	A	MU1A	2014-02-26
Amount	UoM	Unit type	ST ECOPACK Grade	
484.70	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	10.3x7.5x2.25	36	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7a' exemption (other selected exemptions may apply)	true
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	GEGH*UK40AA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	18.745	mg	supplier	die	Silicon (Si)	7440-21-3		17.922	mg	956095	36975
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.118	mg	6295	243
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.118	mg	6295	243
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.143	mg	7629	295
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.029	mg	1547	60
die (s)				supplier	passivation	Indium Tin oxide (In2O3.SnO2)	50926-11-9		0.276	mg	14724	569
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.010	mg	533	21
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.027	mg	1440	56
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.091	mg	4855	188
die (s)				supplier	polymer die coating	Polymer resist (Black resist)	Proprietary		0.011	mg	587	23
Leadframe	Copper & its alloys	161.653	mg	supplier	alloy	Copper (Cu)	7440-50-8		155.397	mg	961300	320604
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		3.655	mg	22610	7541
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.220	mg	1361	454
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.191	mg	1182	394
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		2.190	mg	13548	4518
Die attach		11.366	mg	JIG R	glue or tape	Lead (Pb)	7439-92-1	7a-Lead in high me	11.082	mg	975013	22864
Die attach				supplier	glue or tape	Silver (Ag)	7440-22-4		0.170	mg	14957	351
Die attach				supplier	glue or tape	Tin (Sn)	7440-31-5		0.114	mg	10030	235
Bonding wire		1.237		supplier	wire	Gold (Au)	7440-57-5		1.225	mg	990299	2527
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		0.007	mg	5659	14
Bonding wire				supplier	wire	Palladium (Pd)	7440-05-3		0.004	mg	3234	8
Bonding wire				supplier	wire	Platinum (Pt)	7440-06-4		0.001	mg	808	2
encapsulation		287.916	mg	supplier	mold compound	Phenol Resin	205830-20-2		11.517	mg	40001	23761
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		8.637	mg	29998	17819
encapsulation				supplier	mold compound	epoxy resin	Proprietary		8.637	mg	29998	17819
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.576	mg	2001	1188
encapsulation				supplier	mold compound	silica vitreous	60676-86-0		258.549	mg	898002	533421
connections coating	Solder	5.973	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.973	mg	1000000	12323